NL17SZ07

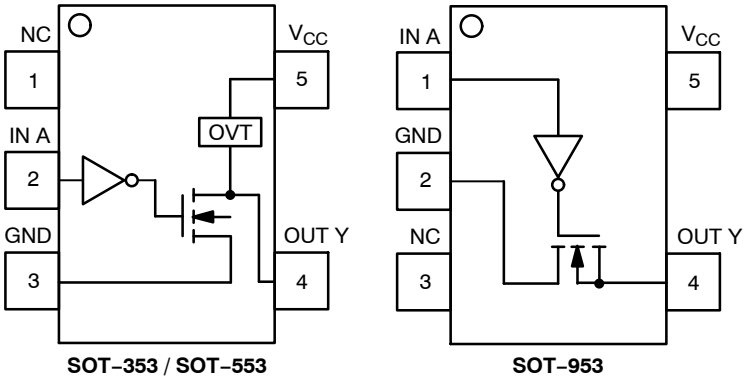
Single Non-Inverting Buffer with Open Drain Output

The NL17SZ07 is a high performance single non−inverting buffer with open drain outputs operating from a 1.65 to 5.5 V supply.

The Output stage is open drain with Over Voltage Tolerance. This allows the NL17SZ07 to be used to interface 5.0 V circuits to circuits of any voltage between 0 and +7.0 V.

Features

- Tiny SOT−353, SOT−553 and SOT−953 Packages
- Extremely High Speed: t_{PD} 2.5 ns (typical) at V_{CC} = 5 V
- Designed for 1.65 V to 5.5 V V_{CC} Operation, CMOS Compatible
- Over Voltage Tolerant Inputs V_{IN} may be Between 0 and 7.0 V for V_{CC} Between 0.5 and 5.5 V
- TTL Compatible − Interface Capability with 5.0 V TTL Logic with V_{CC} = 2.7 V to 3.6 V
- LVCMOS Compatible
- 24 mA Output Sink Capability, Pullup may be between 0 and 7.0 V
- Near Zero Static Supply Current Substantially Reduces System Power Requirements
- Chip Complexity: FET = 20
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC−Q100 Qualified and PPAP Capable
- These Devices are Pb−Free and are RoHS Compliant



SOT−353 / SOT−553 **SOT−953**

Figure 1. Pinout

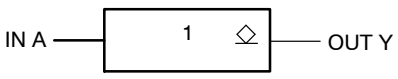


Figure 2. Logic Symbol

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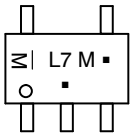
MARKING DIAGRAMS

SC−88A / SOT−353 / SC−70
DF SUFFIX
CASE 419A



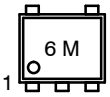
SOT−553
XV5 SUFFIX
CASE 463B

L7 = Device Code
M = Date Code*
▪ = Pb−Free Package

(Note: Microdot may be in either location)

*Date Code orientation and/or position may vary depending upon manufacturing location.

SOT−953
CASE 527AE



6 = Specific Device Code
M = Month Code

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

PIN ASSIGNMENT
(SOT−353 / SOT−553)

Pin	Function
1	NC
2	IN A
3	GND
4	OUT Y
5	V_{CC}

PIN ASSIGNMENT (SOT−953)

Pin	Function
1	IN A
2	GND
3	NC
4	OUT Y
5	V_{CC}

FUNCTION TABLE

Input	Output
A	**Y**
L	L
H	Z

MAXIMUM RATINGS

Symbol	Characteristics		Value	Unit
V_{CC}	DC Supply Voltage		−0.5 to +7.0	V
V_I	DC Input Voltage		$-0.5 \le V_I \le +7.0$	V
V_O	DC Output Voltage (SOT−953 Package)	(Note 1)	−0.5 to V_{CC} + 0.5	V
	DC Output Voltage (SOT−353 / SOT−553 Packages)	Active Mode, LOW State (Note 1) Tri−State Mode Power−Down Mode (V_{CC} = 0 V)	−0.5 to V_{CC} + 0.5 −0.5 to +7.0 −0.5 to +7.0	
I_{OK}	DC Output Diode Current (SOT−953 Package) (SOT−353 / SOT−553 Packages)	 V_O < GND, V_O > V_{CC} V_O < GND	 ±50 −50	mA
I_{IK}	DC Input Diode Current	V_I < GND	−50	mA
I_O	DC Output Sink Current		±50	mA
I_{CC}	DC Supply Current per Supply Pin		±100	mA
I_{GND}	DC Ground Current per Ground Pin		±100	mA
T_{STG}	Storage Temperature Range		−65 to +150	°C
P_D	Power Dissipation in Still Air	SOT−353 SOT−553	186 135	mW
θ_{JA}	Thermal Resistance	SOT−353 SOT−553	350 496	°C/W
T_L	Lead Temperature, 1 mm from Case for 10 Seconds		260	°C
T_J	Junction Temperature Under Bias		+150	°C
$I_{Latch-Up}$	Latch−Up Performance	Above V_{CC} and Below GND at 85°C (Note 5)	±500	mA
MSL	Moisture Sensitivity		Level 1	
F_R	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V−0 @ 0.125 in	
ESD	ESD Classification	Human Body Model (Note 3) Machine Model (Note 4) Charged Device Model (Note 5)	Class 2 Class B N/A	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. I_O absolute maximum rating must be observed.
2. Tested to EIA/JESD22−A114−A, rated to EIA/JESD22−A114−B.
3. Tested to EIA/JESD22−A115−A, rated to EIA/JESD22−A115−A.
4. Tested to JESD22−C101−A.
5. Tested to EIA/JESD78.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Max	Unit
V_{CC}	Supply Voltage	Operating Data Retention Only	1.65 1.5	5.5 5.5	V
V_I	Input Voltage		0	5.5	V
V_O	Output Voltage (SOT−953 Package)		0	V_{CC}	V
	Output Voltage (SOT−353 / SOT−553 Packages)	Active Mode, LOW State Tri−State Mode Power−Down Mode (V_{CC} = 0 V)	0 0 0	V_{CC} 5.5 5.5	
T_A	Operating Free−Air Temperature		−55	+125	°C
$\Delta t/\Delta V$	Input Transition Rise or Fall Rate	V_{CC} = 2.5 V ±0.2 V V_{CC} = 3.0 V ±0.3 V V_{CC} = 5.0 V ±0.5 V	0 0 0	20 10 5	ns/V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

DC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Condition	V_{CC} (V)	T_A = 25°C			−55°C ≤ T_A ≤ 125°C		Unit
				Min	Typ	Max	Min	Max	
V_{IH}	High−Level Input Voltage		1.65 to 1.95 2.3 to 5.5	0.75 V_{CC} 0.7 V_{CC}			0.75 V_{CC} 0.7 V_{CC}		V
V_{IL}	Low−Level Input Voltage		1.65 to 1.95 2.3 to 5.5			0.25 V_{CC} 0.3 V_{CC}		0.25 V_{CC} 0.3 V_{CC}	V
I_{LKG}	Z−State Output Leakage Current	V_{IN} = V_{IH} V_{OUT} = V_{CC} or GND	2.3 to 5.5			±5.0		±10.0	μA
V_{OL}	Low−Level Output Voltage V_{IN} = V_{IL}	I_{OL} = 100 μA	1.65 to 5.5		0.0	0.1		0.1	V
		I_{OL} = 4 mA	1.65		0.08	0.24		0.24	
		I_{OL} = 8 mA	2.3		0.20	0.3		0.3	
		I_{OL} = 12 mA	2.7		0.22	0.4		0.4	
		I_{OL} = 16 mA	3.0		0.28	0.4		0.4	
		I_{OL} = 24 mA	3.0		0.38	0.55		0.55	
		I_{OL} = 32 mA	4.5		0.42	0.55		0.55	
I_{IN}	Input Leakage Current	V_{IN} = 5.5 V or GND	0 to 5.5			±0.1		±1.0	μA
I_{OFF}	Power Off Leakage Current (SOT−353/ SOT−553 Packages)	V_{IN} = 5.5 V or V_{OUT} = 5.5 V	0			1		10	μA
I_{CC}	Quiescent Supply Current	V_{IN} = 5.5 V or GND	5.5			1		10	μA
I_{CCT}	Quiescent Supply Current	V_{IN} = 3.0 V	3.6			10		100	μA

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

AC ELECTRICAL CHARACTERISTICS $t_R = t_F$ = 2.5 ns; C_L = 50 pF; R_L = 500 Ω

Symbol	Parameter	Condition	V_{CC} (V)	T_A = 25°C			−55°C ≤ T_A ≤ 125°C		Unit
				Min	Typ	Max	Min	Max	
t_{PZL}	Propagation Delay (Figure 3 and 4)	R_{L} = R_1= 500 Ω, C_L = 50 pF	1.8 ± 0.15	0.8	5.3	11.6	0.8	12.0	ns
			2.5 ± 0.2	1.2	3.7	5.8	1.2	6.4	
			3.3 ± 0.3	0.8	2.9	4.4	0.8	4.8	
			5.0 ± 0.5	0.5	2.3	3.5	0.5	3.9	
t_{PLZ}	Propagation Delay (Figure 3 and 4)	R_{L} = R_1= 500 Ω, C_L = 50 pF	1.8 ± 0.15	0.8	5.3	11.6	0.8	1.20	ns
			2.5 ± 0.2	1.2	2.8	5.8	1.2	6.4	
			3.3 ± 0.3	0.8	2.1	4.4	0.8	4.8	
			5.0 ± 0.5	0.5	1.4	3.5	0.5	3.9	

CAPACITIVE CHARACTERISTICS

Symbol	Parameter	Condition	Typical	Unit
C_{IN}	Input Capacitance	V_{CC} = 5.5 V, V_I = 0 V or V_{CC}	> 2.5	pF
C_{OUT}	Output Capacitance	V_{CC} = 5.5 V, V_I = 0 V or V_{CC}	4.0	pF
C_{PD}	Power Dissipation Capacitance (Note 6)	10 MHz, V_{CC} = 5.5 V, V_I = 0 V or V_{CC}	4.0	pF

6. C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: $I_{CC(OPR)} = C_{PD} \bullet V_{CC} \bullet f_{in} + I_{CC}$. C_{PD} is used to determine the no−load dynamic power consumption; $P_D = C_{PD} \bullet V_{CC}^2 \bullet f_{in} + I_{CC} \bullet V_{CC}$.

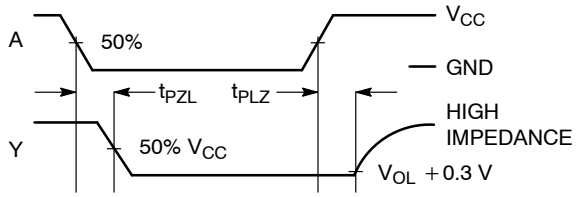
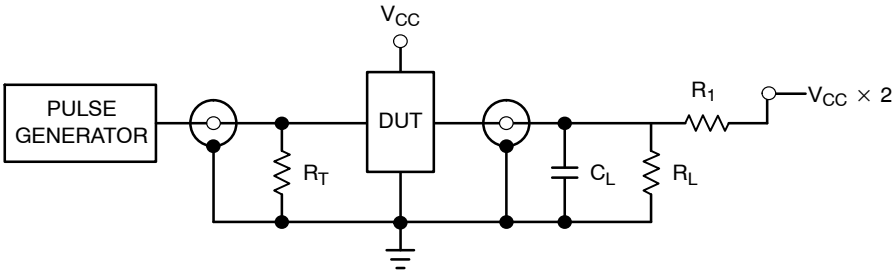


Figure 3. Switching Waveforms



R_T = Z_{OUT} of pulse generator (typically 50 Ω)

Figure 4. Test Circuit

DEVICE ORDERING INFORMATION

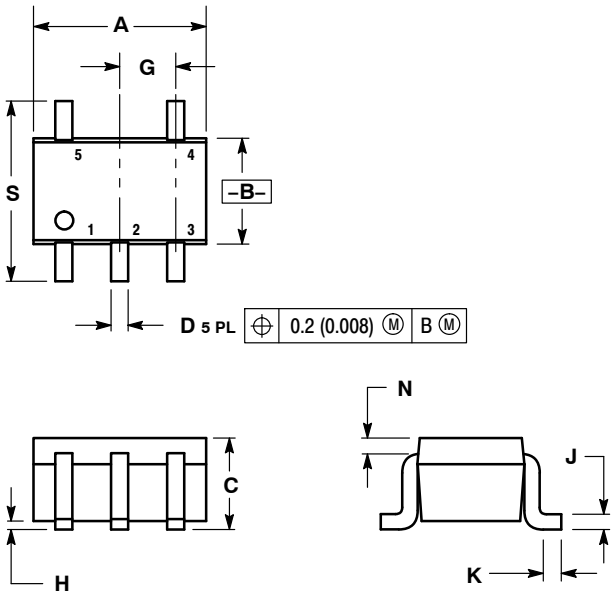
Device	Package	Shipping†
NL17SZ07DFT2G	SOT−353/SC70−5/SC−88A (Pb−Free)	3000 / Tape & Reel
NLV17SZ07DFT2G*	SOT−353/SC70−5/SC−88A (Pb−Free)	3000 / Tape & Reel
NL17SZ07XV5T2G	SOT−553 (Pb−Free)	4000 / Tape & Reel
NL17SZ07P5T5G	SOT−953 (Pb−Free)	8000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC−Q100 Qualified and PPAP Capable.

PACKAGE DIMENSIONS

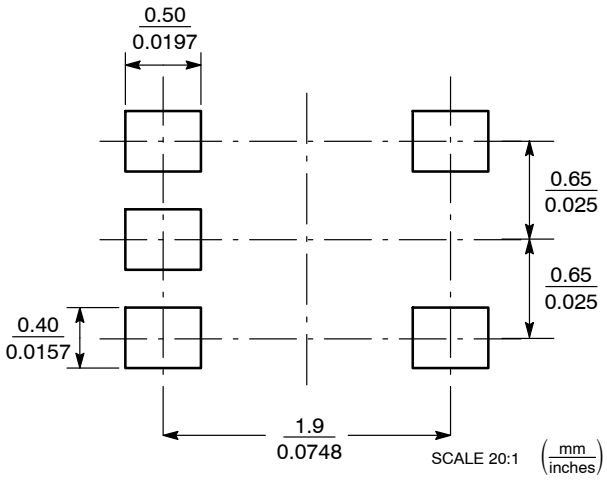
SC−88A (SC−70−5/SOT−353)
CASE 419A−02
ISSUE L



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. 419A−01 OBSOLETE. NEW STANDARD 419A−02.
4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.071	0.087	1.80	2.20
B	0.045	0.053	1.15	1.35
C	0.031	0.043	0.80	1.10
D	0.004	0.012	0.10	0.30
G	0.026 BSC		0.65 BSC	
H	---	0.004	---	0.10
J	0.004	0.010	0.10	0.25
K	0.004	0.012	0.10	0.30
N	0.008 REF		0.20 REF	
S	0.079	0.087	2.00	2.20

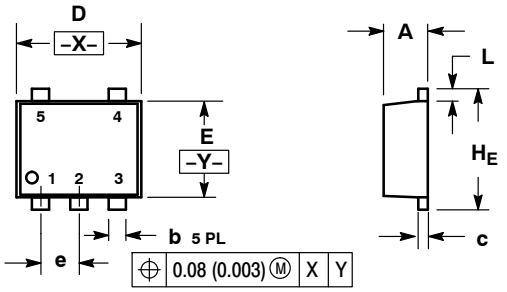
SOLDER FOOTPRINT*



*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

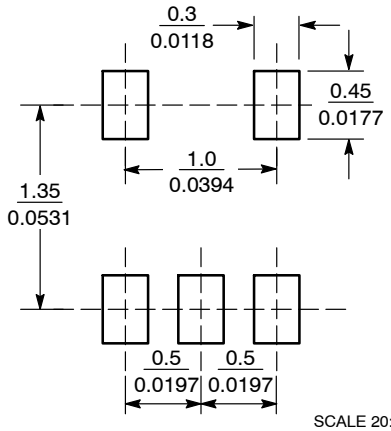
SOT−553
XV5 SUFFIX
CASE 463B
ISSUE B



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
A	0.50	0.55	0.60	0.020	0.022	0.024
b	0.17	0.22	0.27	0.007	0.009	0.011
c	0.08	0.13	0.18	0.003	0.005	0.007
D	1.50	1.60	1.70	0.059	0.063	0.067
E	1.10	1.20	1.30	0.043	0.047	0.051
e	0.50 BSC			0.020 BSC		
L	0.10	0.20	0.30	0.004	0.008	0.012
H_E	1.50	1.60	1.70	0.059	0.063	0.067

SOLDERING FOOTPRINT*

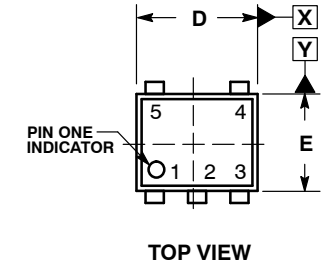


SCALE 20:1 $\left(\frac{\text{mm}}{\text{inches}}\right)$

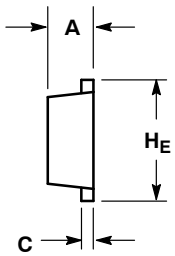
*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

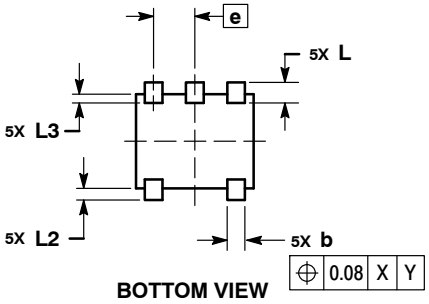
SOT−953
CASE 527AE
ISSUE E



TOP VIEW



SIDE VIEW

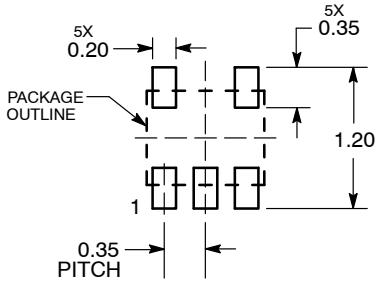


BOTTOM VIEW

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	MILLIMETERS		
DIM	MIN	NOM	MAX
A	0.34	0.37	0.40
b	0.10	0.15	0.20
C	0.07	0.12	0.17
D	0.95	1.00	1.05
E	0.75	0.80	0.85
e	0.35 BSC		
H_E	0.95	1.00	1.05
L	0.175 REF		
L2	0.05	0.10	0.15
L3	−−−	−−−	0.15

SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:
Literature Distribution Center for ON Semiconductor
P.O. Box 5163, Denver, Colorado 80217 USA
Phone: 303−675−2175 or 800−344−3860 Toll Free USA/Canada
Fax: 303−675−2176 or 800−344−3867 Toll Free USA/Canada
Email: orderlit@onsemi.com

N. American Technical Support: 800−282−9855 Toll Free USA/Canada
Europe, Middle East and Africa Technical Support:
Phone: 421 33 790 2910
Japan Customer Focus Center
Phone: 81−3−5817−1050

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